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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
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10/730,758

12/08/2003

David Lee

AZMT-002 P1

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26291

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04/04/2005

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EXAMINER

HA, NATHAN W

ART UNIT

PAPER NUMBER

2814

DATE MAILED: 04/04/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

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Office Action Summary	Application No. 10/730,758	Applicant(s) LEE, DAVID	
	Examiner Nathan W. Ha	Art Unit 2814	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 03 January 2005.
 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-14 is/are pending in the application.
 4a) Of the above claim(s) 12-14 is/are withdrawn from consideration.
 5) ☐ Claim(s) _____ is/are allowed.
 6) ☒ Claim(s) 1-11 is/are rejected.
 7) ☐ Claim(s) _____ is/are objected to.
 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
 a) ☐ All b) ☐ Some * c) ☐ None of:
 1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
 * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|---|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)
Paper No(s)/Mail Date <u>3/04</u> . | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Election/Restrictions

1. Applicant's election without traverse of Claims 1-11 in the reply filed on 1/3/05 is acknowledged.

Double Patenting

2. The nonstatutory double patenting rejection is based on a judicially created doctrine grounded in public policy (a policy reflected in the statute) so as to prevent the unjustified or improper timewise extension of the "right to exclude" granted by a patent and to prevent possible harassment by multiple assignees. See *In re Goodman*, 11 F.3d 1046, 29 USPQ2d 2010 (Fed. Cir. 1993); *In re Longi*, 759 F.2d 887, 225 USPQ 645 (Fed. Cir. 1985); *In re Van Ornum*, 686 F.2d 937, 214 USPQ 761 (CCPA 1982); *In re Vogel*, 422 F.2d 438, 164 USPQ 619 (CCPA 1970); and, *In re Thorington*, 418 F.2d 528, 163 USPQ 644 (CCPA 1969).

A timely filed terminal disclaimer in compliance with 37 CFR 1.321(c) may be used to overcome an actual or provisional rejection based on a nonstatutory double patenting ground provided the conflicting application or patent is shown to be commonly owned with this application. See 37 CFR 1.130(b).

Effective January 1, 1994, a registered attorney or agent of record may sign a terminal disclaimer. A terminal disclaimer signed by the assignee must fully comply with 37 CFR 3.73(b).

Claims 1-2, 4-6 are rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 1-3, 6, 8, 10 of U.S. Patent No. 6,660,562.

In regard to claim 1, the only difference between the currently claim and the cited patent is that the claim 1 does not mention molding sidewalls on the substrate, but instead mentions cavity on the substrate. It should be obvious to one of ordinary skill in the art to recognize that a cavity is comprised of bottom and sides surfaces. By claiming

a cavity on a substrate the claim 1 automatically includes sidewalls of the cavity. For example, claim 5 of the patent further claims these sidewalls.

In regard to claim 2, claim 2 of the cited patent discloses IC die, and combination thereof. IC dies comprise electronic circuits.

In regard to claim 4, see cited patent's claim 3.

In regard to claim 5, see cited patent's claim 6.

In regard to claim 6, see cited patent's claim 10.

Claim Rejections - 35 USC § 103

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 1-7 and 9-11 are rejected under 35 U.S.C. 103(a) as being unpatentable over Miyawaki (US 6,268,236) in view of Mahulikar et al. (US 4,897,508, hereinafter, Mahulikar.)

In regard to claim 1, in figs. 2A-2C, Miyawaki discloses a method of packaging at least one component, comprising:

providing a lid 2;

molding sidewalls 1B, for example, onto a substrate to form a plurality of cavities 4 surrounding a component-mounting surface;

mounting a component 7 on the component-mounting surface in each cavity;

applying a curable adhesive 3 to a top surface of the sidewalls;
placing the lid upon the top surface of the sidewalls;
curing said adhesive; and
separating the component package assembly into a plurality of individual component packages.

Miyawaki, however, does not disclose that the lid having vent holes.

Mahulikar, in fig. 4, discloses an analogous package including a substrate 12, cavity 30, and a component 22 in the cavity, adhesive layer to attach a lid 14 to the substrate. Fig. 4 further discloses a vent hole 44 and seals the vent, or aperture, in the lid for reaction by-products generated during the cure cycle (col. 7, lines 19-21.)

Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention was made to include an aperture in the lid in order to include reaction by-products generated during the cure cycle.

In regard to claim 2, the component 7 as disclosed by Miyawali is a semiconductor chip; all chips compose of electronic circuits, or IC.

In regard to claims 3 and 10, the component as disclosed by Miyawaki is a high-frequency semiconductor chip. It, therefore, includes radio frequency circuit (see also, col. 5, line 33).

In regard to claim 4, Mahulikar discloses the top cover and sidewalls are formed of polymers (col. 5, lines 48-49 and col. 6, lines 10-13.)

In regard to claim 5, the curing the adhesive to seal the package is performed thermally (col. 6, lines 25-26).

In regarding to claim 6, Miyawali further discloses wherein separating comprises sawing, for example, wire saw (col. 4, lines 63-67.)

In regard to claim 7, Miyawali further discloses wherein placing the lid upon the sidewalls comprises applying a substantially uniform pressure over each cavity. (col. 4, lines 34-35.)

In regard to claims 9 and 11, the package as disclosed by Miyawaki includes cavities. These cavities are formed in a normal atmosphere; therefore, they contain air.

5. Claim 8 is rejected under 35 U.S.C. 103(a) as being unpatentable over Miyawaki and Mahulikar as applied to claims 1-7 and 9-11 above, and further in view of Song et al. (US 5,776,799, hereinafter, Song).

In regard to claim 8, the above combination discloses all of the claimed limitations, except the adhesive layer is formed by screen printing.

Song, in fig. 5, for example, discloses a semiconductor package including adhesive layer 142 is deposited by screen printing process in order to allow the adhesive to be applied to many lead attaching regions at one time (col. 5, lines 49-52.)

Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention was made to use a widely used process such screen printing to form the adhesive layer in order to allow the adhesive to be applied to many lead attaching regions at one time.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nathan W. Ha whose telephone number is (571) 272-1707. The examiner can normally be reached on M-TH 8:00-7:00(EST).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



Nathan Ha
March 15, 2005